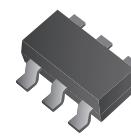


## CSRVO65V0P RoHs Device



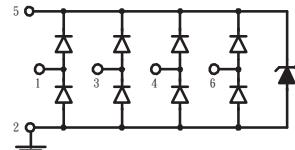
### Features

- ESD Protect for 4 high-speed I/O channels.
- IEC61000-4-2 Level 4 ESD protection.
- IEC61000-4-4 (FET)20A for I/O,80A for Power.
- Working voltage: 5V
- Low capacitance:1.3pF(Typ.).
- High component density.

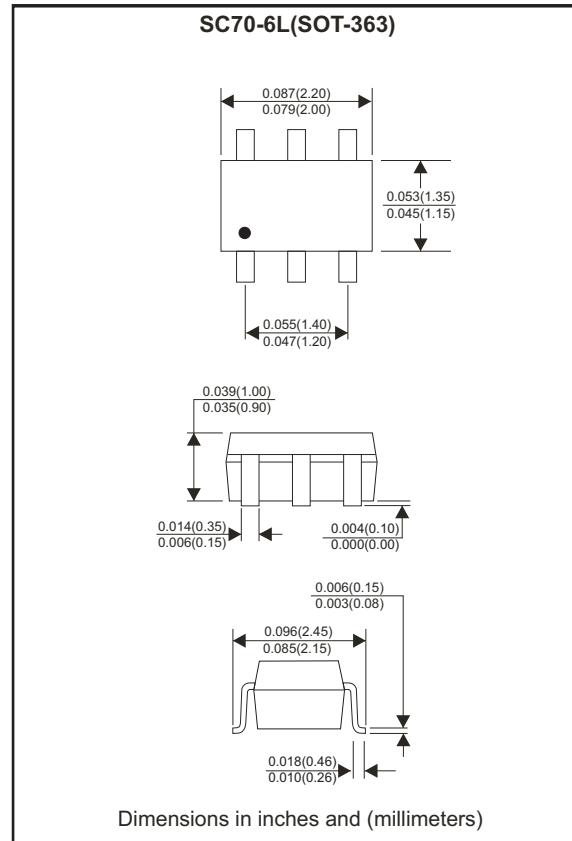
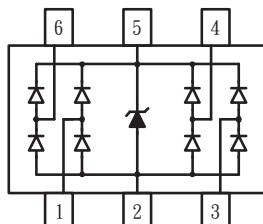
### Mechanical data

- Case: SC70-6L(SOT-363) standard package, molded plastic.
- Terminals: Solder plated, solderable per MIL-STD-750,method 2026.
- Mounting position: Any
- Weight: 0.0091 gram(approx.).

### Circuit Diagram



### Pin Configuration



### Maximum Ratings (at TA=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse current ( tp = 8/20 us)	I <sub>PP</sub>	6.5	A
Operating supply voltage	V <sub>DC</sub>	6	V
ESD per IEC 61000-4-2(Air) ESD per IEC 61000-4-2(Contact)	ESD	18 14	kV
ESD per IEC 61000-4-2(Air)(VDD-GND) ESD per IEC 61000-4-2(Contact)(VDD-GND)	ESD <sub>VDD</sub>	30	kV
Lead soldering temperature	T <sub>SOL</sub>	260 ( 10 sec)	°C
Operating temperature	T <sub>j</sub>	-55 to +85	°C
Storage temperature	T <sub>STG</sub>	-55 to +125	°C
DC voltage at any I/O pin	V <sub>IO</sub>	(GND -0.5) to (VDD +0.5)	V

# Low Capacitance ESD Protection Array

**Comchip**  
SMD Diode Specialist

## Electrical Characteristics (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Reverse stand-Off voltage	Pin 5 to Pin 2	VRWM			5	V
Reverse leakage current	VRWM = 5 V, Pin 5 to Pin 2	IR			5	uA
	V <sub>PIN 5</sub> = 5 V, V <sub>PIN 2</sub> = 0V, V <sub>IO</sub> = 0~5V				1	
Diode breakdown voltage	IR = 1 mA, Pin 5 to Pin 2	V <sub>BD</sub>	6		9	V
Forward voltage	I <sub>F</sub> = 15 mA, Pin 2 to Pin 5	V <sub>F</sub>		0.8	1	V
Clamping voltage	I <sub>PP</sub> = 5 A, tp=8/20us, Any Channel Pin to Ground	V <sub>C</sub>		8.1	9	V
	IEC 61000-4-2 +6kV,Contact mode Any Channel Pin to Ground			12.5		
	IEC 61000-4-2 +6kV,Contact mode VDD Pin to Ground			9		
Junction capacitance	V <sub>pin5</sub> = 5V,V <sub>pin2</sub> = 0V, V <sub>IO</sub> =2.5V, f = 1MHz,Any Channel Pin to Ground	C <sub>J</sub>		1.3	1.6	pF
	V <sub>pin5</sub> = 5V,V <sub>pin2</sub> = 0V, V <sub>IO</sub> =2.5V f = 1MHz,Between Channel Pins			0.12	0.14	
	V <sub>pin5</sub> = 5V,V <sub>pin2</sub> = 0V, V <sub>IN</sub> =2.5V f = 1MHz,Channel_x pin to ground - channel_y pin to ground			0.05	0.07	

# Low Capacitance ESD Protection Array

**Comchip**  
SMD Diode Specialist

## RATING AND CHARACTERISTIC CURVES (CSRV065V0P)

Fig. 1 - Power derating curve

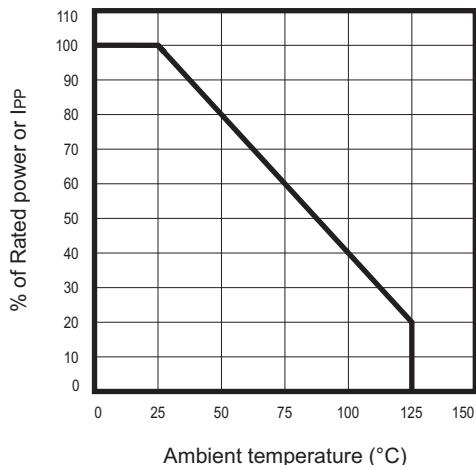


Fig. 2 - Clamping voltage vs. Peak pulse current

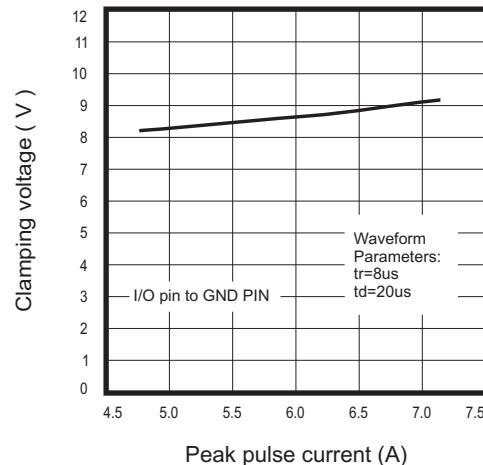


Fig.3 - Forward voltage v.s. forward current

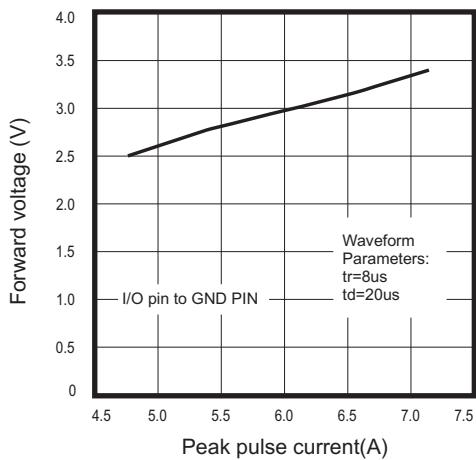


Fig.4 - Typical variation of C<sub>IN</sub> v.s. V<sub>IN</sub>

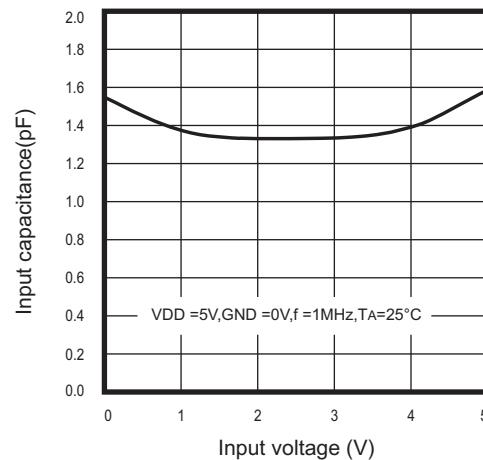


Fig. 5 - Typical variation of C<sub>IN</sub> v.s. temperature

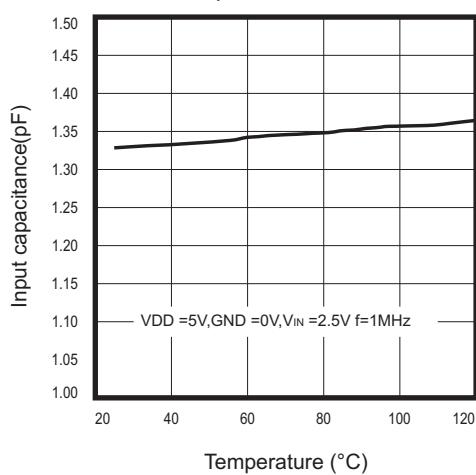


Fig. 6 - Transmission line pulsing (TLP) measurement

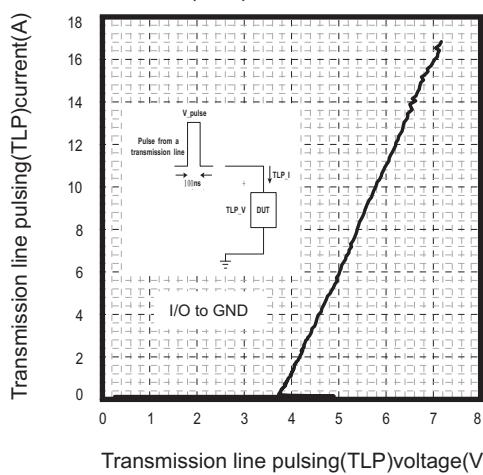
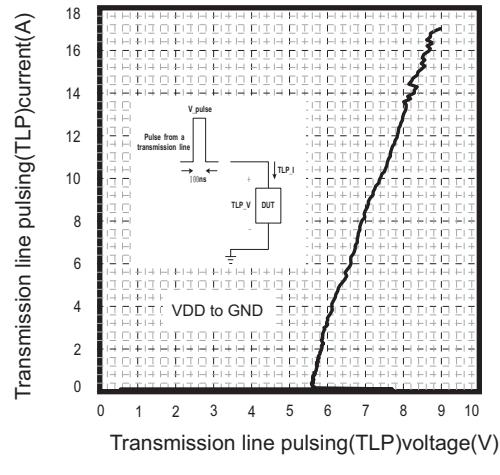
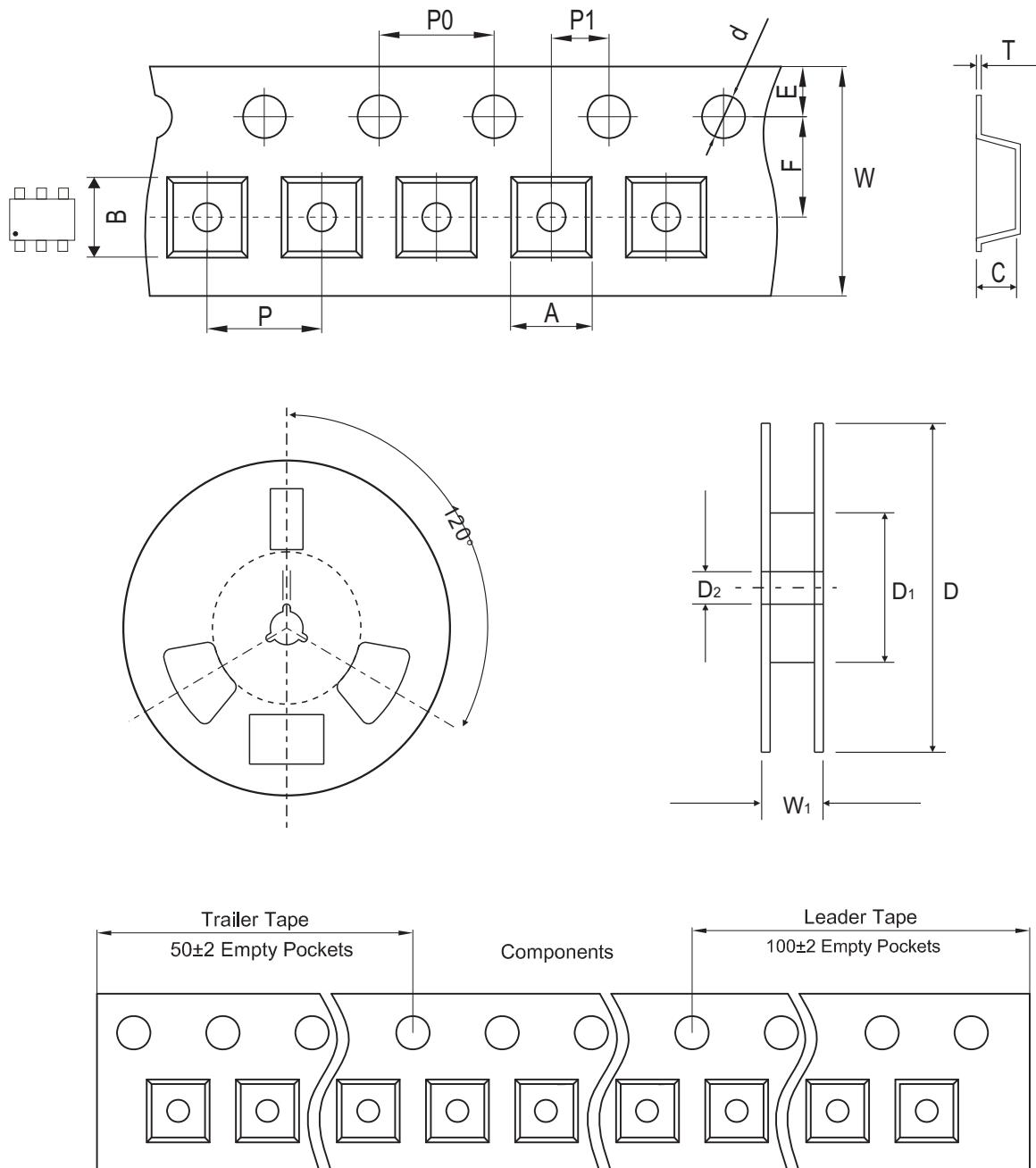


Fig.7 -Transmission line pulsing (TLP) measurement



## Reel Taping Specification

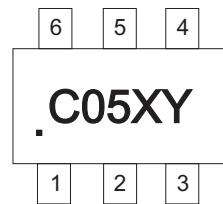


SOT-363	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	$2.25 \pm 0.05$	$2.55 \pm 0.05$	$1.20 \pm 0.05$	$1.50 \pm 0.10$	$178 \pm 2.00$	$54.40 \pm 1.00$	$13.00 \pm 1.00$
	(inch)	$0.089 \pm 0.002$	$0.100 \pm 0.002$	$0.047 \pm 0.002$	$0.059 \pm 0.004$	$7.008 \pm 0.079$	$2.142 \pm 0.039$	$0.512 \pm 0.039$

SOT-363	SYMBOL	E	F	P	$P_0$	$P_1$	W	$W_1$
	(mm)	$1.75 \pm 0.10$	$3.50 \pm 0.10$	$4.00 \pm 0.10$	$4.00 \pm 0.10$	$2.00 \pm 0.10$	$8.00 + 0.30 / - 0.10$	$12.30 \pm 1.00$
	(inch)	$0.069 \pm 0.004$	$0.138 \pm 0.004$	$0.157 \pm 0.004$	$0.157 \pm 0.004$	$0.079 \pm 0.004$	$0.315 + 0.012 / - 0.004$	$0.484 \pm 0.039$

## Marking Code

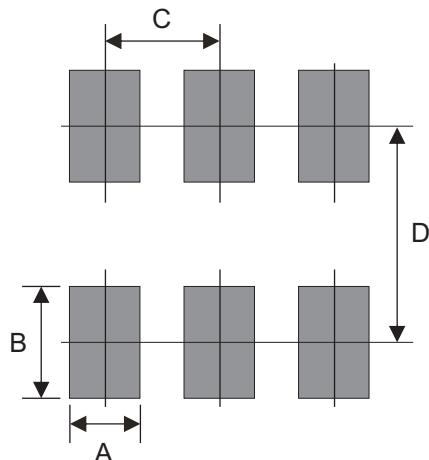
Part Number	Marking Code
CSRV065V0P	C05XY



C05 = Device code  
X = Date Code  
Y = Control Code

## Suggested PAD Layout

SIZE	SOT-363	
	(mm)	(inch)
A	0.40	0.016
B	0.80	0.031
C	0.65	0.026
D	1.94	0.076



## Standard Packaging

Case Type	REEL PACK	
	REEL ( pcs )	Reel Size (inch)
SOT-363	3,000	7